

ON Semiconductor				10/15/2019
Base Part		NCP300	HF	Pb-free
Orderable Part		NCP300LSN28T1G	Total weight (mg)	14.08
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	0.42	Silicon (Si)	7440-21-3	100
Die Attach	0.11	Epoxized Condensate Of Para-Hydrobenzaldehyde And Alkyl Phenol	129915-35-1	32
		Aluminum Trioxide (Al2O3)	1344-28-1	66.8
		Antimony Pentoxide (Sb2O5)	1314-60-9	1.2
Lead Frame	5.78	Silver (Ag)	7440-22-4	1.22
		Zinc (Zn)	7440-66-6	0.12
		Iron (Fe)	7439-89-6	2.35
		Copper (Cu)	7440-50-8	96.28
		Phosphorus (P)	7723-14-0	0.03
Mold Compound-Black	7.34	Phenolic Resin	n/a	5
		Ortho Cresol Novolac Resin	29690-82-2	2
		Epoxy + Phenol Resin	n/a	5
		Carbon Black (C)	1333-86-4	0.5
		Fused Silica (SiO2)	60676-86-0	87.5
Plating	0.39	Tin (Sn)	7440-31-5	100
Wire Bond - Au	0.04	Gold (Au)	7440-57-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

<http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF>